



Product Information Sheet

EPO-TEK® H81A

Date: March 2023
Rev: VI
No. of Components: Two
Mix Ratio by Weight: 61 : 10
Specific Gravity: Part A: 5.80 Part B: 5.62
Pot Life: 2 Days
Shelf Life- Bulk: One year at room temperature

Recommended Cure: 150°C / 1 Hour

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A two component, gold-filled, electrically and thermally conductive epoxy designed for hybrid microelectronic and semiconductor packaging.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Part A: Dark Brown	Part B: Dark Brown
* Consistency:	Thick paste	
* Viscosity (23°C) @ 0.5 rpm:	250,000-300,000	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 100	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	Upon request	
Above Tg:	Upon request	
Shore D Hardness:	Upon request	
Lap Shear @ 23°C:	Upon request	
Die Shear @ 23°C:	≥ 5	Kg 1,778 psi
Degradation Temp:	412	°C
Weight Loss:		
@ 200°C:	< 0.05	%
@ 250°C:	0.07	%
@ 300°C:	0.16	%
Suggested Operating Temperature:	< 350	°C (Intermittent)
Storage Modulus:	Upon request	
* Particle Size:	≤ 50	microns

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	Upon request
* Volume Resistivity @ 23°C:	≤ 0.0009 Ohm-cm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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